REMARKS

In response to the Restriction Requirement mailed on August 3, 2001, Applicants hereby elect Group II, claims 10-33, without transverse.

Claims 10-33 remain in the application. Independent claims 10, 21, and 23 have been amended to more clearly define the present invention. These amendments are supported in the specification at page 10, line 12 et seq. and FIGs. 5, 6a-c, 7, and 8.

An Information Disclosure Statement with a PTO-1449 is enclosed herewith. As no action on the merits has been received, no fee is believed due for the Information Disclosure Statement.

Please forward further communications to the address of record. If the Examiner needs to contact the below-signed attorney to further the prosecution of the application, the contact number is (503) 712-1682.

Respectfully submitted,

Dated: August 31, 2001

Robert G. Winkle
Attorney for Applicants
Reg. No. 37,474

VERSION OF CLAIMS WITH MARKINGS

IN THE CLAIMS:

10. (First Amended) A method of fabricating microelectronic dice, comprising:

providing a first encapsulated die assembly having an active surface and a back surface, said first encapsulated die assembly including at least one first microelectronic die having an active surface and at least one side and a first packaging material adjacent said at least one first microelectronic die side, wherein said first packaging material comprises a first microelectronic package core and a first encapsulation material, and wherein said first encapsulation material comprises at least a portion of said first encapsulation die assembly back surface; [and]

providing a second encapsulated die assembly having an active surface and a back surface, said second encapsulated die assembly including at least one second microelectronic die having an active surface and at least one side and a second packaging material adjacent said at least one second microelectronic die side; and

attaching said first encapsulated die assembly back surface to said second encapsulated assembly back surface.

21. (First Amended) The method of claim 10, wherein said providing a first encapsulated die assembly comprises:

providing at least one first microelectronic die having an active surface and at least one side;

abutting a protective film against said at least one first microelectronic die

active surface;

abutting said first microelectronic package core against said protective film;

encapsulating said at least one microelectronic die with an encapsulation material adjacent said at least one first microelectronic die side, wherein said encapsulation material provides at least one surface of said encapsulation material substantially planar to said first microelectronic die active surface; and

removing said protective film.

23. (First Amended) A method of fabricating a microelectronic package, comprising:

forming a first encapsulated die assembly comprising:

providing at least one first microelectronic die having an active surface and at least one side;

abutting a protective film against said at least one first microelectronic die active surface;

abutting a first microelectronic package core against said protective film; and

encapsulating said at least one microelectronic die with an packaging material adjacent said at least one first microelectronic die side to form a first encapsulated die active surface and a first encapsulated die back surface;

forming a second encapsulated die assembly comprising:

providing at least one second microelectronic die having an active surface and at least one side;

abutting a protective film against said at least one second microelectronic die active surface; and

encapsulating said at least one microelectronic die with an packaging material adjacent said at least one second microelectronic die side to form a second encapsulated die active surface and a second encapsulated die back surface; and

attaching said first encapsulated die assembly back surface to said second encapsulated assembly back surface.